

11-01-2001

Docket No.: XA-9525

FORM PTO-1595 (Modified)  
(Rev. 03-01)  
OMB No. 0651-0027 (exp. 5/31/2002)  
P08A/REV03



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U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Katsutoshi NAKAYAMA, Satoshi KOJIMA, and  
Syouhei ODA

10-12-01

## 2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Address: 6, Kanda Surugadai 4-chome

Chiyoda-ku

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

## 3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Tokyo

State/Prov.:

Country: Japan

ZIP:

Execution Date: September 20 and 25, 2001

Additional name(s) &amp; address(es)

☐ Yes ☒ No

## 4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

PCT/JP99/00675

17 February 1999

09913021

Additional numbers

☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mitchell W. Shapiro

Registration No. 31,568

Address: Miles &amp; Stockbridge P.C.

1751 Pinnacle Drive

Suite 500

City: McLean

State/Prov.: Virginia

Country: U.S.

ZIP: 22102

## 6. Total number of applications and patents involved:

1

## 7. Total fee (37 CFR 3.41): \$ 40.00

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mitchell W. Shapiro

Name of Person Signing

Signature

October 11, 2001

Date

2

Total number of pages including cover sheet, attachments, and

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PATENT  
REEL: 012289 FRAME: 0859

# ASSIGNMENT ( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## STORAGE MEDIUM AND METHOD OF FABRICATING SEMICONDUCTOR INTEGRATED CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Katsutoshi Nakayama (Katsutoshi NAKAYAMA)

20 / September / 2001

2) Satoshi Kojima (Satoshi KOJIMA)

25 / September / 2001

3) Syouhei Oda (Syouhei ODA)

20 / September / 2001

4) \_\_\_\_\_

5) \_\_\_\_\_

6) \_\_\_\_\_

7) \_\_\_\_\_

8) \_\_\_\_\_

9) \_\_\_\_\_

10) \_\_\_\_\_